



Inline XL

Optimized system for n-type inline application

Features & Benefit



Various inline application

- HF/Metal Cleaning
- RCA & O3 Cleaning
- Developing / Etching / Striping
- Electrical deposition



Various cleaning solutions

- Roller brush / Disc brush
- Bubble jet
- Ultrasonic / Plasma



Capable Si wafer size

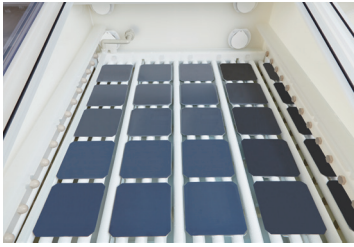
up to 210mm x 210 mm (M12 size)



Particle free design



Perfect Drying



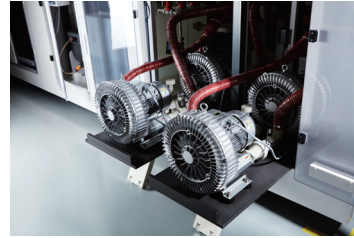
Inline system



Inline Wet process



High pressure Spray cleaning



Easy Maintenance

Process outline



Technical Data

Application	HF & Metal cleaning / RCA & O3 Cleaning / D.E.S / Electrical deposition	
	PERC / n-PERT / TopCon / HIT / IBC	
Dimensions	10 Lane: 12,000 (L) x 3,380 (W) x 2,680 (H) mm	5 Lane: 12,000 (L) x 2,000 (W) x 2,680 (H) mm
Transport height	970mm +/- 50mm	
Thoughtput	10 Lane: up to 8,000 w/h	5 Lane: up to 4,000 w/h
Substrate size & thickness	up to 210mm x 210 mm (M12 size)	> 120 μm as-cut
Conveyor speed & wafer gap	0.8m/min ~ 3.2m/min	20mm wafer to wafer
Heater	Stainless steel / Quartz / Teflon coated / Electrical coil	
Circulation pump	Magnetic / Bellows / Barrel	
PLC control	Mitsubishi / Allen-Bradley / Siemens / others	
Certification	CE / UL / ISO 9001 / ISO 14001	
Options	Chilling system (acidic texturing)	Integrated electrical cabinet
	Integrated Ozone system	Feed & bleed system
	Conductivity / pH meter	